

# **ABS22 THRU ABS210**

# SINGLE PHASE GLASS PASSIVATED BRIDGE RECTIFIERS

# **FEATURES**

Ideal for printed circuit board Reliable low cost construction utilizing molded plastic technique High temperature soldering guaranteed: 260°C/10 seconds at 5 lbs., (2.3kg) tension Small size, simple installation High surge current capability Glass passivated chip junction

# **MECHANICAL DATA**

Case: Molded plastic body

Terminals: Plated leads solderable per MIL-STD-750,

Method 2026

Polarity: Polarity symbols marked on case

Mounting Position: Any

# 0.000(5.1) 0.193(3.45) 0.193(3.45) 0.193(3.45) 0.193(3.45) 0.193(3.45) 0.193(3.45) 0.193(3.45) 0.193(3.45) 0.193(3.45) 0.193(3.45) 0.193(3.45) 0.193(3.45) 0.193(3.45) 0.193(3.45) 0.193(3.45) 0.193(3.45) 0.193(3.45) 0.193(3.45) 0.193(3.45)

**ABS** 

Dimensions in inches and (millimeters)

# MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

Ratings at 25°C ambient temperature unless otherwise specified.

Single phase half-wave 60Hz, resistive or inductive load, for capacitive load derate current by 20%.

	SYMBOLS	ABS22	ABS24	ABS26	ABS28	ABS210	UNITS
Maximum repetitive peak reverse voltage	Vrrm	200	400	600	800	1000	VOLTS
Maximum RMS voltage	VRMS	140	280	420	560	700	VOLTS
Maximum DC blocking voltage	VDC	200	400	600	800	1000	VOLTS
Maximum average forward rectified current				•			
On glass-epoxy P.C.B.(Note1)	I <sub>F(AV)</sub> 2.0						Amps
On aluminum substrate(Note2)		2.0					'
Peak forward surge current,							
8.3ms single half sine-wave superimposed on	IFSM 50						Amps
rated load (JEDEC Method)							'
Maximum instantaneous forward voltage drop	VF	4.0					1/-1/-
per leg at 1.0A	VF 1.0					Volts	
Maximum DC reverse current Ta=25℃		5					uA
at rated DC blocking voltage Ta=100°C	IR 100					uA	
Typical thermal resistance(NOTE 3)	RθJL	15 50					
	RθJA						°C/W
	LAJA						
Operating temperature range	TJ	-55 to +150					$\mathbb{C}$
storage temperature range	Тѕтс	-55 to +150					°C

NOTES:1.On glass epoxy P.C.B. mounted on 0.05x0.05"(1.3x1.3mm) pads

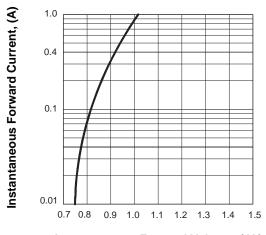
2.On aluminum substrate P.C.B. with on area of 0.8"x0.8"(20x20mm) mounted on 0.05X0.05"(1.3X1.3mm) solder pad

3.Thermal resistance form junction to ambient and junction to lead mounted on P.C.B. with 0.2X0.2"(5X5mm) copper pads.



# RATINGS AND CHARACTERISTIC CURVES ABS22 THRU ABS210

# FIG.1 TYPICAL FORWARD CHARACTERISTICS



Instantaneous Forward Voltage, (V)

### FIG.2 FORWARD DERATING CURVE

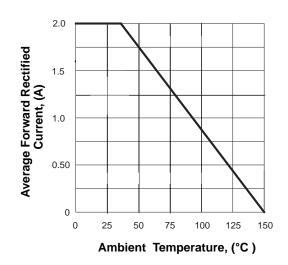
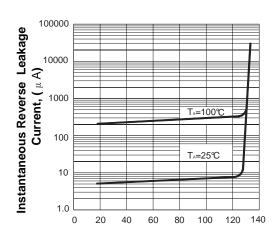
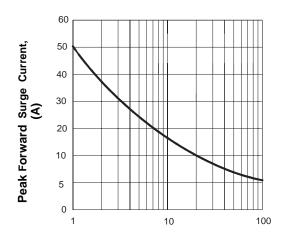


FIG.3 TYPICAL REVERSE CHARACTERISTICS



Percent Of Rated Peak Reverse Voltage, %

# FIG.4 PEAK FORWARD SURGE CURRENT



Number Of Cycles At 60Hz

# 单击下面可查看定价,库存,交付和生命周期等信息

# >>ZG(中鑫半导体)